



Wah Wang Data Sheet For 0805 Green SMD

Part No: WW-GIS170TS-G



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S.D.N. or D.N. No. : _____

Customer Name : _____

Sample Approval Signature : _____

Date : _____

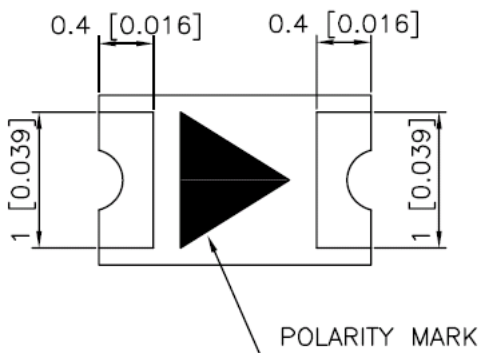
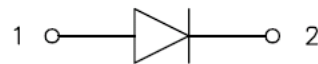
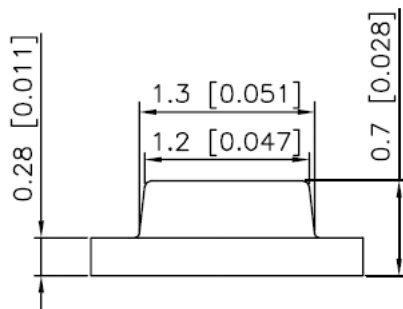
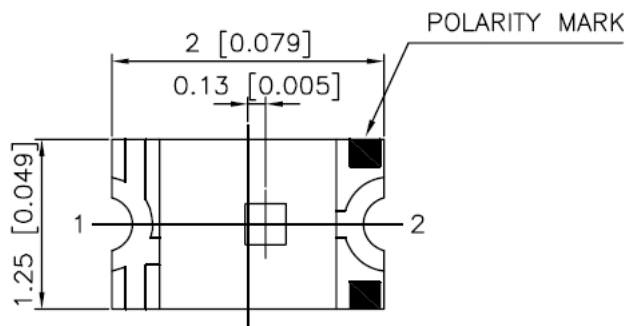


Features

- 1. Chip LED.
- 2. SMD LED dimensions: 2.0(L) x 1.25(W) x 0.7(H) mm
- 3. High intensity
- 4. Extremely wide view angle
- 5. Anti-electrostatic tape package
- 6. Reliable and stable

| | |
|-----------------------|---------------|
| Part No. | WW-GIS170TS-G |
| Lens Color | Water Clear |
| Emitting Color | Green |
| Resin (mold) | Epoxy |

Package Dimension



**Absolute Maximum Ratings at Ta=25**

| Parameter | MAX. | Unit |
|--|------------|------|
| Power Dissipation | 100 | mW |
| Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width) | 100 | mA |
| Continuous Forward Current | 25 | mA |
| Reverse Voltage | 5 | V |
| Operating Temperature Range | -40 to +85 | |
| Storage Temperature Range | -40 to +85 | |

Electrical Optical Characteristics at Ta=25

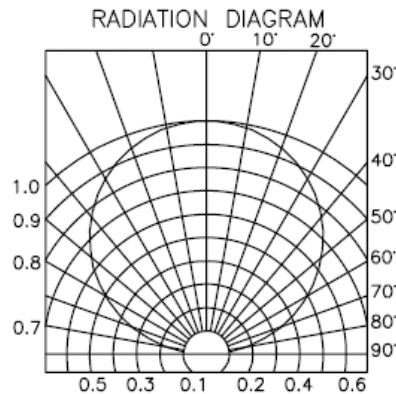
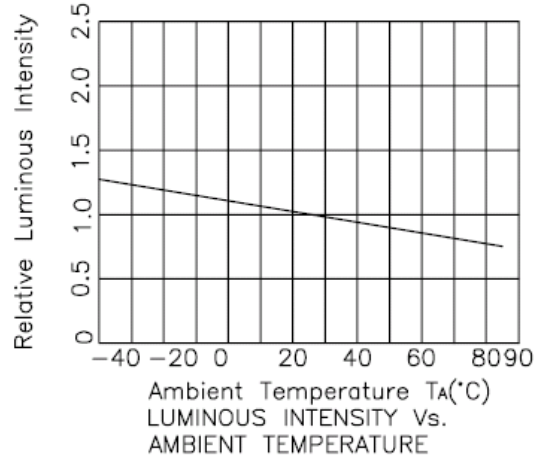
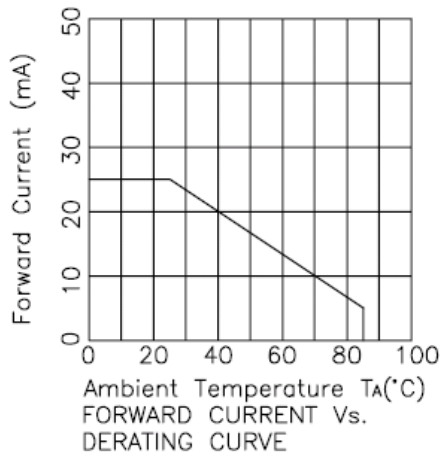
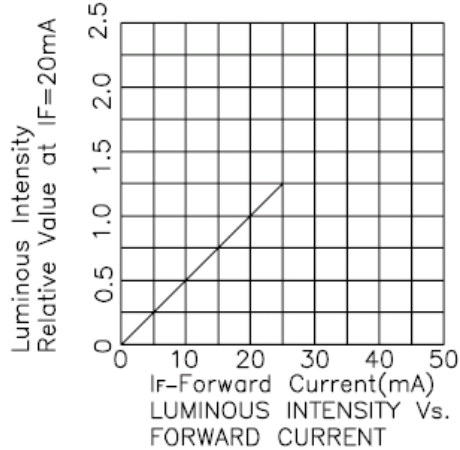
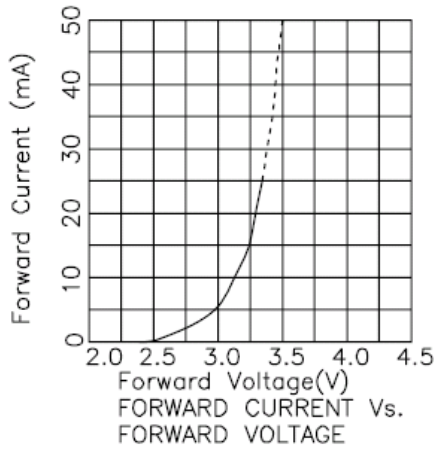
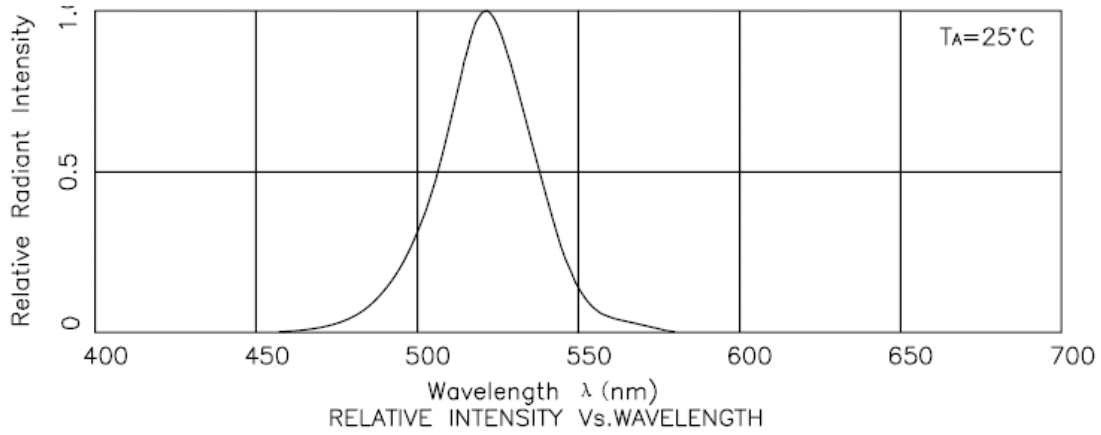
| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test Condition |
|--------------------|-------------------|------|------|------|------|--------------------------------|
| Luminous Intensity | I _v | 385 | --- | 845 | mcd | I _F = 20mA (Note 7) |
| Viewing angle | 2θ _{1/2} | --- | 120 | --- | Deg | (Note 8) |
| Wavelength | λD | 515 | --- | 525 | nm | I _F = 20mA(Note 9) |
| Forward Voltage | V _F | 2.8 | --- | 3.6 | V | I _F = 20mA |
| Reverse Current | I _R | --- | --- | 10 | μA | V _R = 5V |

Notes:

- All dimensions are in millimeter.
- Tolerance is ±0.25mm(.01") unless others otherwise noted.
- Protruded resin under flanges is 1.0mm(0.4") max.
- Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.
- Caution in ESD: Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
- Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
- θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- It use many parameters that correspond to the CIE 1931 2°
X,Y, and Z are CIE1931 2° values of Red, Green and Blue content of the measurement.



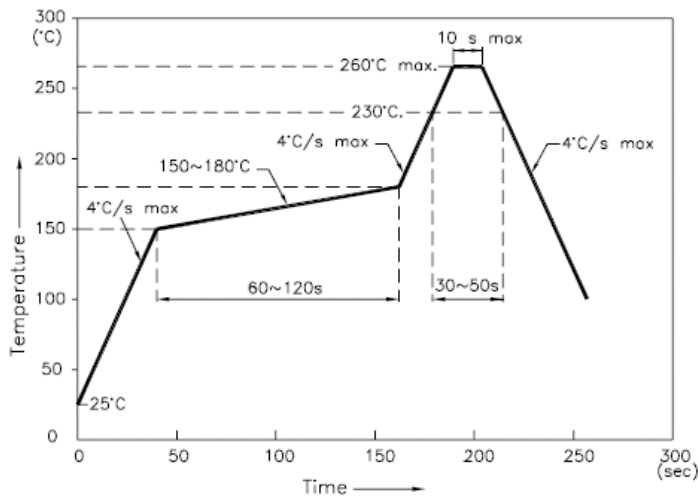
◆ Typical Electrical/Optical Characteristics Curves





◆ Soldering Profile

Reflow Soldering Profile For Lead-free SMT Process.

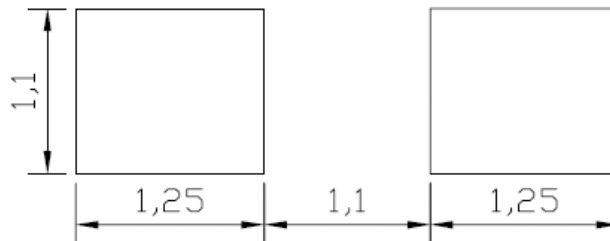


NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

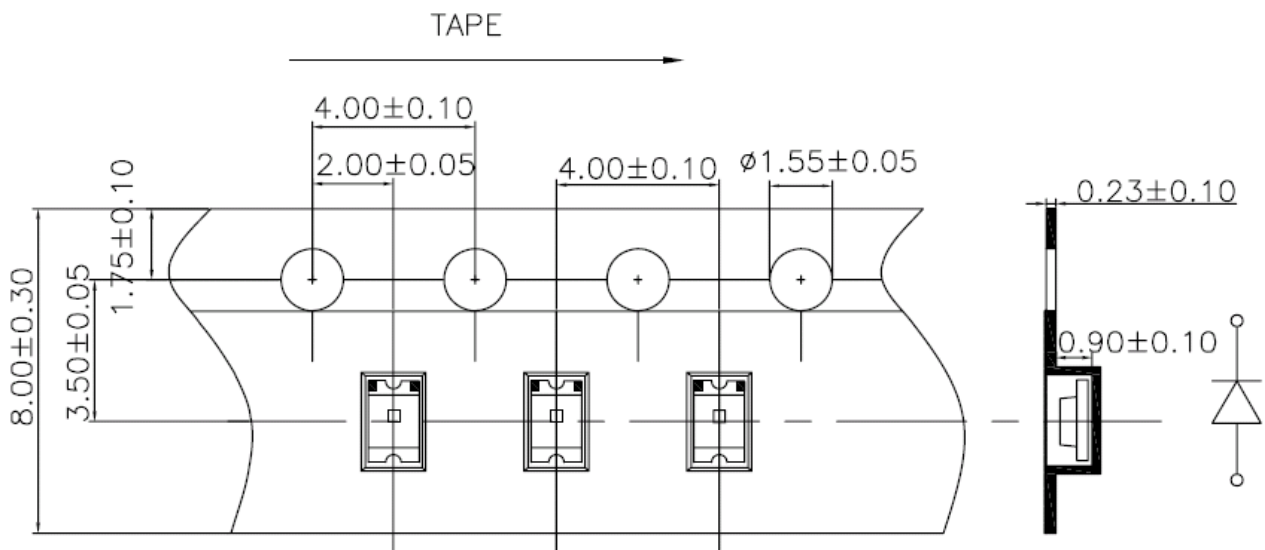
◆ Recommended soldering pattern

(Units:mm)



◆ Tape specifications

(Units:mm)

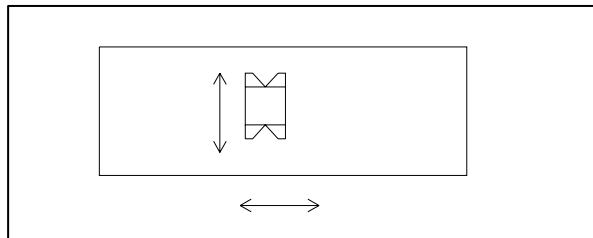




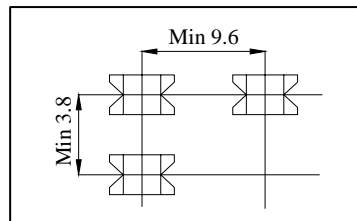
CAUTIONS- SMD LED

Precaution to be taken in designing apparatus using SMD LED:

- (1) The current limiting resistor must be provided in the driving circuit of SMD LED and the circuit should be designed so as to drive SMD LED within the rated value:
Care must be taken to design of the apparatus so that the momentary reverse voltage (or excessive current) is not be charged to SMD LED when the circuit is turned ON or OFF.
- (2) Care must be taken to design the circuit so that the average current is within the rated value of SMD LED if the pulse driving is adapted. And also the circuit should be designed so that the reverse voltage is not charged to SMD LED when the SMD LED is turned off.
- (3) For reflow soldering, the accuracy of SMD LED is within +/- 0.3mm approximately in "X" and "Y" directions. (In case of dip soldering, it is dependent on mounting accuracy.)
- (4) SMD LED is raised by 0 to 0.3mm approximately after soldering.
- (5) In order to avoid the stress in soldered area that may be caused by bending of the circuit board, mounting of SMD LED at a right against longer sided of the circuit board is recommended as illustrated below.
- (6) The pitch between SMD LED should be 3.8 X 9.6mm minimum as illustrated below. .



- (7) When assembling the circuit board into the finished products, care must be taken to avoid the component parts from touching other parts.



Others

- (1) Care must be taken not to cause stress to the epoxy resin portion of SMD LED while it is exposed to high temperature.
- (2) Care must be taken not to the rub the epoxy resin portion of SMD LED with a hard or sharp edged article such as the sand blast and the metal hook as the epoxy resin is rather soft and liable to be damaged.